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APPLICATION NO. FILING DATE FIRST NAMED INVENTOR ATTORNEY DOCKET NO. F AMAT/1931 08/856,116 05/14/97 CHEN **EXAMINER** MMC2/0227 PERALTA, G PATENE COUNSEL **ART UNIT** PAPER NUMBER APPLIED MATERIALS INC P 0 B0X 450 A 2814 SANTA CLARA CA 95052 **DATE MAILED:** 02/27/01

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

<u> </u>	Application No.	Applicant(s)	
Advisory Action	08/856,116	CHEN ET AL.	
	Examiner	Art Unit	
	Ginette Peralta	2814	
The MAILING DATE of this communication appe		L :	
THE REPLY FILED FAILS TO PLACE THIS APPRINGED FAILS TO PLACE THIS APPRINGED FOR THE PROPERTY FAILS TO PLACE THIS APPRINGED FOR THE PROPERTY FILE OF APPRINCED FOR THE PROPERTY FILE OF APPRINCED FOR THE PROPERTY FILE OF T	 a timely filed amendment which 	ation. A proper reply to a chiphaces the application in	ed .
PERIOD FOR R	EPLY [check only a) or b)]		
 a) The period for reply expires 3 months from the mailing date o b) In view of the early submission of the proposed reply (within tw reply expires on the mailing date of this Advisory Action, OR c whichever is later. In no event, however, will the statutory period mailing date of the final rejection. 	vo months as set forth in MPEP § 706.07 ontinues to run from the mailing date of the	e final rejection,	•
Extensions of time may be obtained under 37 CFR 1.136(a). The dath have been filed is the date for purposes of determining the period of exten 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened (b) above, if checked. Any reply received by the Office later than three moderned patent term adjustment. See 37 CFR 1.704(b).	sion and the corresponding amount of the d statutory period for reply originally set in t	fee. The appropriate extension fee un the final Office action; or (2) as set for	nder th in
1. A Notice of Appeal was filed on <u>01 December 2000</u> 37 CFR 1.192(a), or any extension thereof (37CFF	. Appellant's Brief must be filed R 1.191(d)), to avoid dismissal o	within the period set forth in f the appeal.	
2. The proposed amendment(s) will be entered upon with requisite fees.	the timely submission of a Noti	ce of Appeal and Appeal Brie	ef .
3. \square The proposed amendment(s) will not be entered by	ecause:		
(a) \(\square\) they raise new issues that would require furth	er consideration and/or search.	(see NOTE below);	
(b) $\hfill\Box$ they raise the issue of new matter. (see Note	below);		
(c) ☐ they are not deemed to place the application issues for appeal; and/or	in better form for appeal by mate	erially reducing or simplifying	the
(d) they present additional claims without cancel NOTE:	ling a corresponding number of t	inally rejected claims.	
4. Applicant's reply has overcome the following reject	ion(s):		
5. Newly proposed or amended claim(s) would canceling the non-allowable claim(s).	be allowable if submitted in a s	eparate, timely filed amendm	ent
6. ☑ The a) ☐ affidavit, b) ☐ exhibit, or c) ☑ request for application in condition for allowance because: See		idered but does NOT place ti	he
7. The affidavit or exhibit will NOT be considered be raised by the Examiner in the final rejection.	ecause it is not directed SOLELY	to issues which were newly	
8. For purposes of Appeal, the status of the claim(s)	is as follows (see attached writte	en explanation, if any):	
Claim(s) allowed:			
Claim(s) objected to:			
Claim(s) rejected: <u>15-18, 23</u> .			
Claim(s) withdrawn from consideration:			
9. The proposed drawing correction filed on a	a)∐has b)∐ has not been app	roved by the Examiner.	
10. Note the attached Information Disclosure Stateme	ent(s)(PTO-1449) Paper No(s).	,	
11. ☐ Other:			

Continuation of 6. does NOT place the application in condition for allowance because: Applicant is directed to Figs. 5-11 of Taguchi et al. where a first barrier layer 21 is deposited over a blanket dielectric layer, a feature is formed through the barrier layer and the dielectric layer, a second barrier layer 22 is deposited on the bottom and sidewalls of the feature, the second barrier layer is removed from the bottom of the feature and a metal layer is deposited on the underlayer exposed in the feature. Thus the reference does teach the removal of the second barrier layer prior to the deposition of the metal layer.

OLIK CHAUDHURI SUPERVISORY PATENT EXAMINER

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TECHNOLOGY CENTER 2800